



Title of Change:	Qualification of Maxchip Electronic Corp. (MXP) in Taiwan as an additional wafer fab site for the listed products.		
Proposed first ship date:	14 March 2017 <i>or earlier upon customer approval.</i>		
Contact information:	Contact your local ON Semiconductor Sales Office or <Osamu.Akaki@onsemi.com>		
Samples:	Contact your local ON Semiconductor Sales Office		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Yasuhiro.Igarashi@onsemi.com>		
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.		
Change Part Identification:	Affected products will be identified with date code.		
Change category:	☒ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other _____		
Change Sub-Category(s):	☒ Manufacturing Site Change/Addition ☐ Material Change ☐ Datasheet/Product Doc change ☐ Manufacturing Process Change ☐ Product specific change ☐ Shipping/Packaging/Marking ☐ Other: _____		
Sites Affected:	☐ All site(s) ☐ not applicable ☐ ON Semiconductor site(s) : _____ ☒ External Foundry/Subcon site(s) Maxchip Electronics Corp.		
Description and Purpose:			
This Final Product/Process Change Notification (FPCN) announces the addition of Maxchip Electronics Corp (MXP) as a wafer fabrication site for the list of ON Semiconductor products below. Maxchip Electronics Corp. (MXP) is located in Hsinchu, Taiwan, and is ISO9001 certified. The product design and electrical specifications will not change. A full electrical characterization over the temperature range is performed for each product to check the device functionality and electrical specifications. Qualification tests are designed to show that the reliability of the affected products will continue to meet or exceed ON Semiconductor standards.			

**Reliability Data Summary:**

QV DEVICE NAME: EFC6612R-TF

PACKAGE: CSP-6 / EFCP3517-6DGH-020

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 80% max rated VSSS	1008 hrs	0/231
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs	0/231
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/75
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	0/75
TC	JESD22-A104	Ta= -45°C to +125°C	850 cyc	0/231
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/75
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/75

Electrical Characteristic Summary:

There is no change in the electrical performance. Datasheet specifications remain unchanged.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
EFC6601R-TR	EFC6612R-TR
EFC4621R-TR	